

Data sheet acquired from Harris Semiconductor SCHS043B – Revised July 2003

CMOS Micropower Phase-Locked Loop

Phase-Locked Loop (PLL) consists of a low-power, linear voltage-controlled oscillator (VCO) and two different phase comparators having a common signal-input amplifier and a common comparator input. A 5.2-V zener diode is provided for supply regulation if necessary.

The CD4046B types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (NSR suffix), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

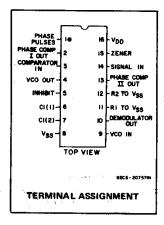
VCO Section

The VCO requires one external capacitor C1 and one or two external resistors (R1 or R1 and R2). Resistor R1 and capacitor C1 determine the frequency range of the VCO and resistor R2 enables the VCO to have a frequency offset if required. The high input impedance (1012 Ω) of the VCO simplifies the design of low-pass filters by permitting the designer a wide choice of resistor-tocapacitor ratios. In order not to load the low-pass filter, a source-follower output of the VCO input voltage is provided at terminal 10 (DEMODULATED OUTPUT). If this terminal is used, a load resistor (RS) of 10 $k\boldsymbol{\Omega}$ or more should be connected from this terminal to VSS. If unused this terminal should be left open. The VCO can be connected either directly or through frequency dividers to the comparator input of the phase comparators. A full C'MOS logic swing is available at the output of the VCO and allows direct coupling to frequency dividers such as the RCA-CD4024, CD4018, CD4020, CD4022, CD4029, and CD4059 One or more CD4018 (Presettable Divide-by-N Counter) or CD4029 (Presettable Up/Down Counter), or CD4059A (Programmable Divide-by-"N" Counter), together with the CD4046B (Phase-Locked Loop) can be used to build a micropower low-frequency synthesizer. A logic 0 on the INHIBIT input "enables" the VCO and the source follower, while a logic 1 "turns off" both to minimize stand-by power consump-

CD4046B Types

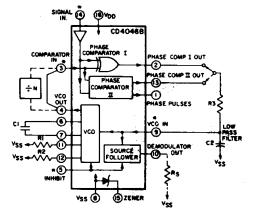
Features:

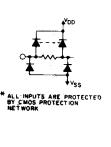
- Very low power consumption:
 70 μW (typ.) at VCO f_o = 10 kHz, V_{DD} = 5 V
- Operating frequency range up to 1.4 MHz (typ.) at $V_{DD} = 10 \text{ V}$, RI = 5 k Ω
- Low frequency drift: 0.04%/°C (typ.) at VDD = 10 V
- Choice of two phase comparators:
 Exclusive-OR network (I)
 Edge-controlled memory network with phase-pulse output for lock indication (II)
- High VCO linearity: <1% (typ.) at VDD = 10 V</p>
- VCO inhibit control for ON-OFF keying and ultra-low standby power consumption
- Source-follower output of VCO control input (Demod. output)
- Zener diode to assist supply regulation
- Standardized, symmetrical output characteristics
- 100% tested for quiescent current at 20 V
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"



Applications:

- FM demodulator and modulator
- Frequency synthesis and multiplication
- Frequency discriminator
- Data synchronization
- Voltage-to-frequency conversion
- Tone decoding
- FSK Modems
- **■** Signal conditioning
- (See ICAN-6101) "RCA COS/MOS Phase-Locked Loop — A Versatile Building Block for Micropower Digital and Analog Applications"





9203 - 29172

Fig.1 - CMOS phase-locked loop block diagram.

MAXIMUM RATINGS, Absolute-Maximum Values: DC SUPPLY-VOLTAGE RANGE, (VDD)

Voltages referenced to VSS Terminal)	0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS	0.5V to V _{DD} +0.5V
DC INPUT CURRENT, ANY ONE INPUT	±10mA
POWER DISSIPATION PER PACKAGE (PD):	
For T _A = -55°C to +100°C	500mW
For T _A = +100°C to +125°C	
DEVICE DISSIPATION PER OUTPUT TRANSISTOR	
FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package	Types) 100mW
OPERATING-TEMPERATURE RANGE (TA)	55°C to +125°C
STORAGE TEMPERATURE RANGE (Tstg)	65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):	
At distance 1/16 \pm 1/32 inch (1.59 \pm 0.79mm) from case for 10s m	ax+265 ⁰ C

Phase Comparators

The phase-comparator signal input (terminal 14) can be direct-coupled provided the signal swing is within CMOS logic levels [logic "0" ≤30% (VDD-VSS), logic "1" ≥ 70% (VDD-VSS)]. For smaller swings the signal must be capacitively coupled to the self-biasing amplifier at the signal input.

Phase comparator I is an exclusive-OR network; it operates analagously to an overdriven balanced mixer. To maximize the lock range, the signal- and comparator-input frequencies must have a 50% duty cycle. With no signal or noise on the signal input, this phase comparator has an average output voltage equal to VDD/2. The low-pass filter connected to the output of phase comparator

RECOMMENDED OPERATING CONDITIONS at T_A = Full Package-Temperature Range For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIN	UNITS	
	Min.	Max.]
Supply-Voltage Range VCO Section:			
As Fixed Oscillator	3	18	1
Phased-Lock-Loop Operation	5	18	l v
Supply-Voltage Range Phase Comparator Section:			1
Comparators	3	18	1
VCO Operation	5	. 18	1 - 1

DESIGN INFORMATION

This information is a guide for approximating the values of external components for the CD4046B in a Phase-Locked-Loop system.

The selected external components must be within the following ranges:

 $5~\text{k}\Omega \leqslant \text{R1, R2, R}_{\text{S}} \leqslant 1~\text{M}\Omega$ C1 \geqslant 100 pF at $\text{V}_{\text{DD}} \geqslant 5~\text{V};$ C1 \geqslant 50 pF at $\text{V}_{\text{DD}} \geqslant$ 10 V

Characteristics	Phase Comparator Used	Design Inf	ormation					
VCO Frequency	1	VCO WITHOUT OFFSET R2 = ∞ MAX To To To To To To To VCO INPUT VOLTAGE	VCO WITH OFFSET					
For No Signal Input	1 2	Same as for No.1 VCO will adjust to center frequency, fo						
Frequency Lock Range, 2 f	1	VCO will adjust to lowest operating frequency, f _{min} 2 f _L = full VCO frequency range 2 f _L = f _{max} -f _{min}						
Frequency Capture Range, 2 f _C	2	Same as for No.1	(1), (2) $2 f_{\mathbb{C}} \approx \frac{1}{\pi} \sqrt{\frac{2\pi f_{\mathbb{L}}}{\sigma 1}}$					
Loop Filter Component Selection	. 1	IN R3 OUT	2 °C ≈ π∜ τ1 For 2 fC, see Ref. (2)					
	2	f _C = f _L						
Phase Angle Between Signal and Comparator	1	$90^{\rm O}$ at center frequency ($f_{\rm O}$) and $180^{\rm O}$ at ends of lock ran	approximating 0 ⁰ ge (2 fL)					
	2	Always 0° in lock						
Locks On Harmonic of Center Frequency	. 1		Yes .					
Signal Input	1	No His						
Noise Rejection	2	Hig Lov						

For further information, see

- (1) F. Gardner, "Phase-Lock Techniques" John Wiley and Sons, New York, 1966
- (2) G. S. Moschytz, "Miniaturized RC Filters Using Phase-Locked Loop", BSTJ, May, 1965.

I supplies the averaged voltage to the VCO input, and causes the VCO to oscillate at the center frequency (f_0).

The frequency range of input signals on which the PLL will lock if it was initially out of lock is defined as the frequency capture range (2f_C).

The frequency range of input signals on which the loop will stay locked if it was initially in lock is defined as the frequency lock range ($2f_L$). The capture range is \leq the lock range.

With phase comparator I the range of frequencies over which the PLL can acquire lock (capture range) is dependent on the low-pass-filter characteristics, and can be made as large as the lock range. Phase-comparator I enables a PLL system to remain in lock in spite of high amounts of noise in the input signal.

One characteristic of this type of phase comparator is that it may lock onto input frequencies that are close to harmonics of the VCO center-frequency. A second characteristic is that the phase angle between the signal and the comparator input varies between $0^{\rm O}$ and $180^{\rm O}$, and is $90^{\rm O}$ at the center frequency. Fig. 2 shows the typical, triangular, phase-to-output response characteristic of phase-comparator I. Typical waveforms for a CMOS phase-locked-loop employing phase comparator I in locked condition of $f_{\rm O}$ is shown in Fig. 3.

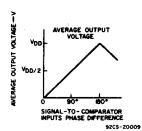


Fig.2 - Phase-comparator I characteristics at low-pass filter output.

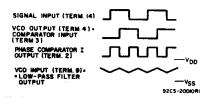


Fig. 3—Typical waveforms for CMOS phase-locked loop employing phase comparator in locked condition of f₀.

Phase-comparator II is an edge-controlled digital memory network. It consists of four flip-flop stages, control gating, and a three-state output circuit comprising p- and n-type drivers having a common output node. When the p-MOS or n-MOS drivers are ON they pull the output up to VDD or down to VSS, respectively. This type of phase comparator acts only on the positive edges of the signal and comparator inputs. The duty cycles of the signal and comparator inputs are not important since positive transitions

CHARAC- TERISTIC	CONI	OITIO	NS	LIMI	TS AT II	NDICATI	ED TEM	IPERA	TURES (°C)	NIT
•	ν _ο (ν)	V _{IN}	V _{DD}	-55	-40	+85	+125	Min.	+25 Tue	Mex.	s
VCO Section		(4)	107		40	700	7120	MHN.	Тур.	MEX.	<u> </u>
	0.4	_ ^ E	5	0.64	0.04	0.40	0.00	0.54	· •	· · · · · · · · · · · · · · · · · · ·	γ-
Output Low (Sink) Current	0.4	0,5 0,10	10	0.64	0.61 1.5	0.42	0.36	0.51	1		ł
IOL Min.	1.5	0.15	15	1.6 4.2	4	1.1 2.8	0.9 2.4	1.3°	2.6 6.8	=	ł
	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	_	,,
Output High (Source)	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	┢▔	∤ ‴
Current,	9.5	0.10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	<u> </u>	1
IOH Min.	13.5	0.15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	┢ <u>╼</u>	i
Output Voltage:	Term. 4	0.5	5		0	.05			0	0.05	t
Low-Level,	driving	0,10	10			.05			0	0.05	4
VOL Max.	смоѕ	0.15	15	-		.05	-		0	0.05	4
	l	0,5	5	 		.95		4.95	5	0.00	ł۲
Output Voltage:	e.g.	0,10	10			95		9.95	10		┨
High-Level, VOH Min.	Term.3	0,15	15			95		14.95	15	-	
Input Current I _{IN} Max.	_	0,18	18	±0.1	±0.1	±1	±1	_	±10 ^{—5}	±0.,1	μ
Phase Comparator S	ection				:	*	<u> </u>	•	•	•	_
Total Device	<u> </u>	0,5	5			0.2		-	0.1	0.2	Т
Current, IDD Max.	_	0,10	10			1			0.5	1	1,,
Term. 14 open,	_	0,15	15	i e			0.75	1.5	ľ		
Term. 5 = V _{DD}	_	0,20	20	1.5					2	4	1
	_	0,5	5			20		-	10	20	T
Term. 14 = V _{SS}		0,10	10	<u> </u>		40		-	20	40	۱,
or V _{DD} , Term. 5	<u> </u>	0,15	15	 		80			40	80	ľ
= V _{DD}	_	0,20	20			160			80	160	1
	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	_	t
Output Low (Sink) Current	0.5	0.10	10	1.6	1.5	1.1	0.9	1.3	2.6	-	1
IOL Min.	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	_	1
Output High	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	_	١,,
(Source)	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	-	ľ
Current	9.5	0,10	10	-1.6	-1.5	-1.1	-0.9	-1.3		├──	ł
I _{OH} Min.	13.5	0,15	15	-4.2	-1.5	-2.8	-2.4	-3.4		Ξ	ł
DC-Coupled Signal Input and Comparator Input Voltage Sensitivity Low Level VIL Max.	0545	_ _ _	5 10			1.5			<u>-</u> -	1.5 3	1
	0.5,4.5	<u> </u>	5			3.5	 	3.5	 	+-	1
High Level	1,9	-	10			3.5		3.5	┝ <u>╌</u>	⊢	1
V _{IH} Min.	. 1.37	_				. /		. /		. –	ŀ

control the PLL system utilizing this type of comparator. If the signal-input frequency is higher than the comparator-input frequency, the p-type output griver is maintained ON most of the time, and both the n and p drivers OFF (3 state) the remainder

of the time. If the signal-input frequency is lower than the comparator-input frequency, the n-type output driver is maintained ON most of the time, and both the n and p drivers OFF (3 state) the remainder of the time. If the signal- and comparator-

input frequencies are the same, but the signal input lags the comparator input in phase, the n-type output driver is maintained ON for a time corresponding to the phase difference. If the signal- and comparator-input frequencies are the same, but

STATIC ELECTRICAL CHARACTERISTICS

CHARAC- TERISTIC	CO	NDITIO	NS	LIMITS AT INDICATED TEMPERATURES (°C)							
*** ***	V _O	VIN	VDD						s		
	(S)	(V)	(V)	-55	–4 0	+85	+125	Min.	Тур.	Max.]
Phase Comparator	Section	(cont'd)								-
Input Current IJN Max. (except Term.14)	ı	0,18	18	±0.1	±0,1	±1	±1		±10 ⁻⁵	±0.1	μΑ
3-State Leakage Current, IOUT Max.	0,18	0,18	18	±0.1	±0.1	±0.2	±0.2		±10 ⁻⁵	±0.1	μА

^{*}Limit determined by minimum feasible leakage current measurement for automatic testing.

ELECTRICAL CHARACTERISTICS at TA = 25°C

CHARAG-					LIMITS	:	
TERISTIC	TEST	CONDITIONS	V _{DD}	-	LL TYP	ES	UNITS
4, 11	l		(v)	Min.	Typ.	Max.	
VCO Section	 	<u> </u>					
Operating Power	f _o = 10 kHz	$R_1 = 1 M\Omega$	5	_	70	140	
Dissipation, P _D	R ₂ = ∞	$VCO_{IN} = \frac{V_{DD}}{2}$	10 15	1 - 1	800 3000	1600 6000	μW
Maximum	C ₁ =50 pF		5	0.3	0.6	_	
Operating Frequency f _{max}	R ₂ = ∞ VCO _{IN} =V _{DD}	$R_1 = 10 k\Omega$	10	0.6	1.2	. –	
		:	15	8.0	1.6		MHz
	C ₁ = 50 pF		5	0.5	0.8	-	
	R ₂ = ∞ VCO _{IN} =V _{DD}	$R_1 = 5 k\Omega$	10	1	1.4	-	
<u>*</u>	TOOIN TOO	<u> </u>	15	1.4	2.4	<u> </u>	
Center Frequency (f _O) and Frequency Range (f _{max} -f _{min})	Programmable with external components R1, R2, and C1						
'max 'min)	See Design Information						
	VCO _{IN = 2.5 V}	±0.3V, R ₁ =10 kΩ	5	-	1.7	_	
	=5 V ±			_	0.5		-
Linearity		$2.5 \text{ V}, =400 \text{ k}\Omega$	10		4		%
		$\pm 1.5 \text{ V}, = 100 \text{ k}\Omega$			0.5	. —	
-	= 7.5 V	$\pm 5 \text{ V}, = 1 \text{ M}\Omega$	15	_	7	<u> </u>	
Temperature - Frequency			5	_	±0.12		
Stability:			10	_	±0.12		
No Frequency	2		15	_	±0.015		
Offset f _{MIN} = 0	- -						%/°C
Frequency			5	-	±0.09		707 C
Offset			10		±0.07	_	
f _{MIN} ≠ 0			15	_	±0.03		
Output Duty Cycle			5,10,15	_	- 50	_	- %
Output Transition			5	_	100	200	· · · · · ·
Times,	**************************************		10		50	100	ns
tTHL, tTLH			15	_	40	80	

the comparator input lags the signal in phase, the p-type output driver is maintained ON for a time corresponding to the phase difference. Subsequently, the capacitor voltage of the low-pass filter connected to this phase comparator is adjusted until the signal and comparator inputs are equal in both phase and frequency. At this stable point both pand n-type output drivers remain OFF and thus the phase comparator output becomes an open circuit and holds the voltage on the capacitor of the low-pass filter constant. Moreover the signal at the "phase pulses" output is a high level which can be used for indicating a locked condition. Thus, for phase comparator II, no phase difference exists between signal and comparator input over the full VCO frequency range. Moreover, the power dissipation due to the lowpass filter is reduced when this type of phase comparator is used because both the p- and n-type output drivers are OFF for most of the signal input cycle. It should be noted that the PLL lock range for this type of phase comparator is equal to the capture range. independent of the low-pass filter. With no signal present at the signal input, the VCO is adjusted to its lowest frequency for phase comparator II. Fig. 10 shows typical waveforms for a CMOS PLL employing phase comparator II in a locked condition.

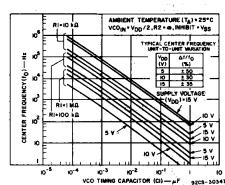


Fig. 4 - Typical center frequency as a function of C1 and R1 at V_{DD} = 5 V, 10 V, and 15 V.

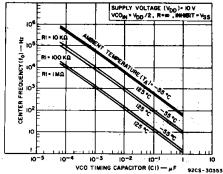


Fig. 5 — Center frequency as a function of C1 and R1 for ambient temperatures of -55°C to 125°C.

ELECTRICAL CHARACTERISTICS at TA = 25°C

CHARAC-			l		LIMITS		
TERISTIC	TES	T CONDITIONS	VDD		LL TYP		UNITS
VCO Section (cont	<u> </u> 'd)) (V)	Min.	Тур.	Max.	
Source-Follower	[1	
Output (Demodu- lated Output): Offset Voltage VCOIN—VDEM	RS	> 10 kΩ	5 10 15	- - -	1.8 1.8 1.8	2.5 2.5 2.5	v
Linearity	R _S =100 kΩ = 300 kΩ =500 kΩ	5 10 15	- - -	0.3 0.7 0.9	- - -	%	
Zener Diode Voltage (V _z)	Ι _Ζ	= 50 μA		4.45	5.5	6.15	v
Zener Dynamic Resistance, R _z	l ₂	= 1 mA		_	40		Ω
Phase Comparator S	ection						
Term. 14 (SIGNAL IN) Input Resistance R ₁₄			5 10 15	1 0.2 0.1	2 0.4 0.2	- - -	МΩ
AC Coupled Signal Input Voltage Sensi- tivity* (peak- to-peak)		= 100 kHz, wave	5 10 15	 	180 330 900	360 660 1800	mV
Propagation Delay Times, Terms. 14 to 1: High to Low Level, tpHL			5 10 15	_ _ _	225 100 65	450 200 130	ns
Low to High Level, tpLH			5 10 15	- - -	350 150 100	700 300 200	ns
3-State Propagation Delay Times, Terms. 3 to 13: High Level to High Impedance, ^t PHZ			5 10 15	-	225 100 95	450 200 190	ns
Terms. 14 to 13: Low Level to High Impedance, ^t PLZ		·	5 10 15	 - - -	285 130 95	570 260 190	ns
Input Rise or Fall Times, t _r , t _f Comparator Input, Term. 3	See Fig. 5 fo	5 10 15	_ _ _	_ _ _	50 1 0.3	μs	
Signal Input, Term. 14			5 10 15	- - -	<u>-</u> -	500 20 2.5	μs
Output Transition Times, t _{THL} , t _{TL}	1		5 10 15	-	100 50 40	200 100 80	ns

^{*} For sine wave, the frequency must be greater than 10 kHz for Phase Comparator II.

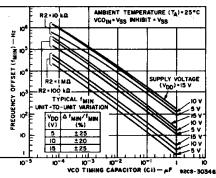


Fig. 6 — Typical frequency offset as a function of C1 and R2 for V_{DD} = 5 V, 10 V, and 15 V.

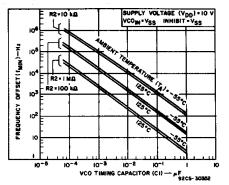


Fig. 7 — Frequency offset as a function of C1 and R2 for embient temperetures of -55°C to 125°C.

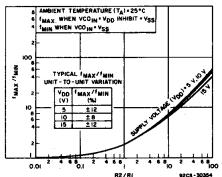


Fig. 8 — Typical f_{MAX}/f_{MIN} as a function of R2/R1.

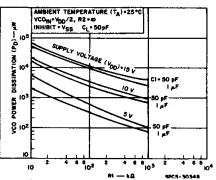


Fig. 9 — Typical VCO power dissipation at center frequency as a function of R1.

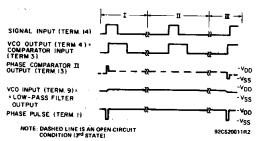


Fig. 10 - Typical waveforms for COS/MOS phase-locked loop employing phase comparator II in locked condition.

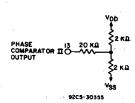


Fig. 11 — Phase comparator II output loading circuit.

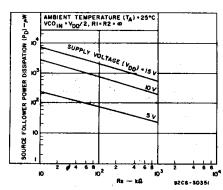


Fig. 13 – Typical source follower power dissipation as a function of Rs.

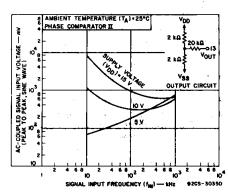
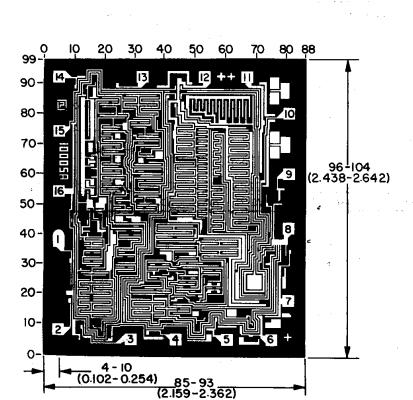


Fig. 14 — AC-coupled signal input voltage as a function of signal input frequency.



92CM-36467 Dimensions and pad layout for CD4046BH.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

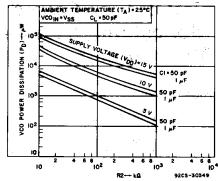


Fig. 12 – Typical VCO power dissipation at f_{MIN} as a function of R2.

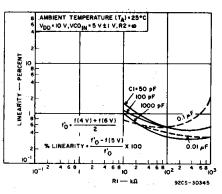


Fig. 15 — Typical VCO linearity as a function of R1 and C1 at V_{DD} = 10 V.

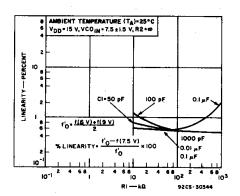


Fig. 16 – Typical VCO linearity as a function of R1 and C1 at V_{DD} = 15 V.



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-9466401MEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
CD4046BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD4046BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD4046BF	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
CD4046BF3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
CD4046BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4046BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4046BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4046BPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4046BPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4046BPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4046BPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4046BPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4046BPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

5-Sep-2011

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL. Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF CD4046B, CD4046B-MIL:

Catalog: CD4046B

Military: CD4046B-MIL

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

14-Jul-2012 www.ti.com

TAPE AND REEL INFORMATION

REEL DIMENSIONS





TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4046BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD4046BPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4046BNSR	SO	NS	16	2000	367.0	367.0	38.0
CD4046BPWR	TSSOP	PW	16	2000	367.0	367.0	35.0

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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